

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	195	("5926370" "4918572" "4953058" "4991002" "5225965" "5274193" "5278730" "5331509" "5642276" "6061235" "4450896" "6181556" "4393435" "5986882" "4755146" "4833569" "5014904" "5576642" "5638469" "5674785" "5739585" "5754060" "5835350" "5923796" "5926373" "6059610" "6059610" "6194246" "6249052" "4441140" "4764804" "4837664" "4884168" "4910642" "4933808" "4974317" "5283715" "5287247" "5367434" "5376882" "5384683" "5432913" "5436794" "5466969" "5548481" "5644161" "5675183" "5708566" "5737187" "5751063").pn. ("5812374" "5828125" "5843807" "5856913" "5870285" "5872403" "5901040" "5930115" "5982617" "6005771" "6022196" "6061260" "6069793" "6083772" "6091604" "6122167" "6181555" "6201700" "6212076" "6212076" "4277816" "4296455" "4449164" "4450505" "4459639" "4468717" "4475145" "4485429" "4535385" "4603374" "4628407" "4630096" "4771294" "4774632" "4777406" "4801992" "4813448" "4866344" "4912601" "4916575" "4928206" "4943468" "4956561" "5014161" "5200657" "5214844" "5222014" "5258887" "5268812" "5268814").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 08:26
S2	1579	(361/695).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 11:20
S3	13	("3574815" "3606673" "4012765" "4204248" "4288839" "4298883" "4451973" "4510519" "4589010" "4602315" "4648008").PN. OR ("4991002"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 13:24
S4	2481	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 13:25

S5	1352	S4 and "circuit board"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:25
S6	1	S5 and "flat cable"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:26
S7	113	S5 and "cable"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:31
S8	26	"first circuit board" and "second circuit board" and (heat adj (dissipat\$4) adj device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:35
S9	1238	(361/719).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 13:35
S10	192	(361/721).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 14:39
S11	0	(164/80.3).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 14:40
S12	2971	(165/80.3).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 14:40

S13	2933	S12 not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 14:40
S14	2621	S13 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 14:40
S15	2321	S14 not S5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 14:40
S16	2056	S15 not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 14:41
S17	474	S16 and "circuit board"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:03
S18	0	(361/104.33).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 15:03
S19	1737	(165/104.33).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 15:03
S20	1607	S19 not S2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:03

S21	1505	S20 not S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:03
S22	1483	S21 not S9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:03
S23	1479	S22 not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:03
S24	305	S23 and "circuit board"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:19
S25	17	(("4884168") or ("6442023") or ("6865080") or ("3921201") or ("5606201") or ("6084771") or ("5504378") or ("5003376")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 15:20
S26	13	("3574815" "3606673" "4012765" "4204248" "4288839" "4298883" "4451973" "4510519" "4589010" "4602315" "4648008").PN. OR ("4991002"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:24
S27	23	("3574815" "3606673" "4012765" "4204248" "4288839" "4298883" "4451973" "4510519" "4589010" "4602315" "4648008" "4756081" "4867235" "4933746" "4935086").PN. OR ("5083368").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:25
S28	26	("3024298" "3209062" "3739234" "4332135" "4681995" "4819011" "5329425" "5339214" "5343940" "5549155" "5598320" "5731954" "5755278" "5764483" "5808869" "5842514" "5910883" "5917699" "5926369" "5966286").PN. OR ("6167949").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:26

S29	21	("3187087" "3798506" "4027206" "4625260" "4707726" "5208729" "5228192" "5567986" "5684675" "5719745" "5751553" "5757073" "5779134" "5808417" "6000132" "6020661").PN. OR ("6201695").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:29
S30	24	("3219885" "3220471" "3519889" "3566959" "4027206" "4588023" "4602315" "4899255" "5170325" "5343362" "5461542" "5507092" "5719745" "5808869" "5854738" "5870286" "5927386" "5973921" "6049459").PN. OR ("6201699").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:31
S31	16	("3746081" "3934643" "4370547" "4673030" "5647430" "5771967" "5950712" "6047766").PN. OR ("6209631").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:32
S32	13	("4298904" "4994937" "5272599" "5886872" "6118654").PN. OR ("6349035").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:33
S33	8	("5184283" "5237485" "5272599" "5513073" "6025992" "6025993" "6259602" "6349035").PN. OR ("6882536").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:34
S34	15	("5037313" "5475563" "5526229").PN. OR ("5808869").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 15:39
S35	973	(257/719).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 15:39
S36	1085	(257/717).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/23 15:42
S37	247	S36 and "circuit board"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 15:57

S38	954	(first adj (board, card, circuit card, motherboard)) and (second adj (board, card, circuit card, motherboard)) and ("heat dissipation device" or "heat dissipating device" or "heatsink" or "heat sink" or "heat-sink" or "cooling plate" or "cold plate" or "heat conductor" or "heat conducting means")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 10:33
S39	13	(first adj (board, card, "circuit card", "circuit board", motherboard)) and (second adj (board, card, "circuit card", "circuit board" motherboard)) and ("heat dissipation device" or "heat dissipating device" or "heatsink" or "heat sink" or "heat-sink" or "cooling plate" or "cold plate" or "heat conductor" or "heat conducting means")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 16:00
S40	13	(first adj (board or card or "circuit card" or "circuit board" or motherboard)) and (second adj (board or card or "circuit card" or "circuit board" or motherboard)) and ("heat dissipation device" or "heat dissipating device" or "heatsink" or "heat sink" or "heat-sink" or "cooling plate" or "cold plate" or "heat conductor" or "heat conducting means")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 17:25

S41	98	("5926370" "4918572" "4953058" "4991002" "5225965" "5274193" "5278730" "5331509" "5642276" "6061235" "4450896" "6181556" "4393435" "5986882" "4755146" "4833569" "5014904" "5576642" "5638469" "5674785" "5739585" "5754060" "5835350" "5923796" "5926373" "6059610" "6059610" "6194246" "6249052" "4441140" "4764804" "4837664" "4884168" "4910642" "4933808" "4974317" "5283715" "5287247" "5367434" "5376882" "5384683" "5432913" "5436794" "5466969" "5548481" "5644161" "5675183" "5708566" "5737187" "5751063").pn. ("5812374" "5828125" "5843807" "5856913" "5870285" "5872403" "5901040" "5930115" "5982617" "6005771" "6022196" "6061260" "6069793" "6083772" "6091604" "6122167" "6181555" "6201700" "6212076" "6212076" "4277816" "4296455" "4449164" "4450505" "4459639" "4468717" "4475145" "4485429" "4535385" "4603374" "4628407" "4630096" "4771294" "4774632" "4777406" "4801992" "4813448" "4866344" "4912601" "4916575" "4928206" "4943468" "4956561" "5014161" "5200657" "5214844" "5222014" "5258887" "5268812" "5268814").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 17:25
S42	44	("3601661" "4756081" "4777561" "4858070").PN. OR ("4953058"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 17:30
S43	2	("4991002").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 08:27
S44	1251	(257/722).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 08:58
S45	800	(361/697).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 09:17

S46	500	(174/252).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 09:35
S47	719	(361/709).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 10:06
S48	516	(361/688).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 10:07
S49	150	(361/711).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/24 10:07
S50	24	("4408220" "4442450" "4479140").PN. OR ("4825337"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 10:09
S51	22	("4811165" "4858071" "5229916" "5428190" "5631807" "5708297").PN. OR ("5995370"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 10:13
S52	154	("first board" or "first card" or "first circuitcard" or "first circuit card" or "first motherboard" or "first daughterboard" or "first circuitboard") and ("second board" or "second card" or "second circuitcard" or "second circuit card" or "second motherboard" or "second daughterboard" or "second circuitboard") and ("heat dissipation device" or "heat dissipating device" or "heatsink" or "heat sink" or "heat-sink" or "cooling plate" or "cold plate" or "heat conductor" or "heat conducting means")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 10:43
S53	17	("3352415" "4013188" "4424900" "4897509" "4906494" "5000256" "5095626" "5315480").PN. OR ("5403973"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 10:41

S54	420	("first board" or "first card" or "first circuitcard" or "first circuit card" or "first motherboard" or "first daughterboard" or "first circuitboard" or "first circuit board") and ("second board" or "second card" or "second circuitcard" or "second circuit card" or "second motherboard" or "second daughterboard" or "second circuitboard" or "second circuit board") and ("heat dissipation device" or "heat dissipating device" or "heatsink" or "heat sink" or "heat-sink" or "cooling plate" or "cold plate" or "heat conductor" or "heat conducting means")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 10:44
S55	266	S54 not S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 10:44
S56	0	"first circuit board" and "first surface" and ("first grounding layer" or "first conducting layer" or "first conduction layer") and "second circuit board" and "second surface" and ("second grounding layer" or "second conducting layer" or "second conduction layer") and ("heat dissipation device" or "plate type heat dissipation device")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 08:30
S57	96	"circuit board" and ("conduction layer" or "grounding layer") and ("heat sink" or "heat dissipation device" or "plate type heat dissipation device" or "plate-type heat dissipation device")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 10:38
S58	4	(("20030062602") or ("5218516")). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/06 16:41
S59	6	("first circuit board" and "second circuit board") and ("conduction layer" or "grounding layer") and ("heat sink" or "heat dissipation device" or "plate type heat dissipation device" or "plate-type heat dissipation device")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 10:38

S60	2	("20040218361").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/06 16:43
S61	3198	"slot connector"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 16:43
S62	141601	("361").CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/06 16:43
S63	297	S62 and "slot connector"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:32
S64	50	"copper plate" near "heat sink"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:35
S65	2	("4991002").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/06 17:35
S66	0	S65 and copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:35
S67	1265	copper near "heat sink"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:36

S68	601	S67 and "conductivity"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/06 17:36
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